

Final Product/Process Change Notification Document # : FPCN16790XGR

Issue Date: 9 November 2015

| Title of Change: | nal PCN for wafer fabrication site addition of ON Semiconductor Niigata Co., Ltd. in Niigata, Japan (Group GR). | | | | |
|---|--|--|--|--|--|
| Proposed first ship date: | 6 February 2016 or earlier upon customer approval | | | | |
| Contact information: | Contact your local ON Semiconductor Sales Office | e or < Yasuhiro.lgarashi@onsemi.com> | | | |
| Samples: | Contact your local ON Semiconductor Sales Office | | | | |
| Additional Reliability Data: | Contact your local ON Semiconductor Sales Office | e or < Kazutoshi.Kitazume@onsemi.com>. | | | |
| Type of notification: | This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com> | | | | |
| Change Part Identification: | Affected products will be identified with date cod | | | | |
| Change category: | 🛛 Wafer Fab Change 🔲 Assembly Change 🔲 Test Change 🔲 Other | | | | |
| Change Sub-Category(s): Manufacturing Site Change/ Manufacturing Process Chan Sites Affected: | | Datasheet/Product Doc change Shipping/Packaging/Marking Other: | | | |
| All site(s) Inot applicable ON Semiconductor site(s) : External Foundry/Subcon site(s) ON Niigata, Japan | | | | | |
| Description and Purpose: | | | | | |
| This is a Final Process Change Notification to announce the expanding of conventional manufacturers, Advanced Microelectronic Products Inc. (AMPI) to newly wafer fabrication site. The additional fabrication site is ON Semiconductor Niigata Co., Ltd. (OSNC) located in Niigata, Japan. OSNC obtained ISO9001 certification. | | | | | |
| The product design and electrication | al specifications will remain identical. A full ele | ctrical characterization over the temperature range will be | | | |

performed for each product to check the device functionality and electrical specifications.



Reliability Data Summary:

| Test | Specification | Condition | Interval | Results | |
|--|--|------------------------------------|-----------------------|---------|--|
| SSOL | ED4701/100 | Tj=150°C | 1000hrs | 0/22 | |
| HTRB - | JESD22-A108 | Ta=150°C, max rated V | 1000hrs | 0/22 | |
| | ED4701/100 | | | | |
| нт <u></u> в — | JESD22-A108 | Ta=150°C, max rated V | 1000hrs | 0/22 | |
| | ED4701/100 | | | | |
| THS | ED4701/100 | Ta=85°C, RH=85% | 1000hrs | 0/22 | |
| тс | JESD22-A104 | | 100 сус | 0/22 | |
| | ED4701/100 | Ta= -55°C to +150°C | | | |
| AC | JESD22 A102 | Ta = 121°C, P= 15 PSIG, RH = 100%, | 50hrs | 0/22 | |
| HTSL | JESD22-A103 | Ta=150°C | 1000hrs | 0/22 | |
| | ED4701/200 | | | | |
| PC — | J-STD-020 JESD-A113 | — MSL 1 @ 260 °C | | | |
| | ED4701/001 | | | | |
| RSH | JESD22- B106 | — Ta = 260C, 10 sec | | 0/22 | |
| | ED4701/300 | | | 0/22 | |
| SD — | JSTD002 | Ta 2450 5 and | | 0/22 | |
| | ED4701/300 | Ta = 245C, 5 sec | | 0/22 | |
| trical Characteris e is no change in th | tic Summary: e electrical performance. Datashee | t specifications remain unchanged. | | | |
| of Affected Stand | lard Parts: | | | | |
| Part Number | | | Qualification Vehicle | | |
| MCH3478-TL-H | | | SMP4003-DL-1E | | |
| MCH3478-TL-W | | | SMP4003-DL-1E | | |